

KB-5150 (ANSI : CEM-1)**覆銅箔改性環氧紙芯玻璃布複合基層壓板****特點**

- 優異的沖孔性，最佳沖孔溫度為 45°C~70°C
- 良好的耐熱性和耐濕性及多等級的耐漏電起痕指數 (CTI175V / 300V / 600V)
- 符合 IPC-4101A 的規範要求
- 不推薦作 PTH 制程

Features

- Excellent punching property, the best punching temperature : 45°C~70°C
- Excellent heat resistance, moisture resistance and CTI value.
- IPC-4101A specification is applicable .
- Plated through holes are not recommended for the cellulose core is easily attacked by the electrolyte.

General Properties 一般特性

Test Item 測試項目	Unit 單位	Test Method (IPC-TM-650) 測試方法	Test Condition 處理條件	Spec (IPC-4101A) 規格值	Typical Value 典型值
Peel Strength (10Z) 銅箔剝離強度	kgf/cm	2.4.8	A	≥1.43	1.70
			Float 260°C / 10Sec	≥1.40	1.65
Thermal stress 熱應力	Sec	2.4.13.1	Float260°C/unetched	≥10	30
Bow / Twist 彎弓度/翹曲度	%	2.4.22.1	A	≤ 1.0(DSB)	0.3 / 0.4
				≤ 1.5(SSB)	
Flexural Strength 抗彎強度	N/mm ²	2.4.4	Warp	≥242	420
			Fill	≥172	290
Flammability 燃燒性	Rating	UL94	UL-94	UL94 V-0	V-0
Surface Resistance 表面電阻	MΩ	2.5.17.1	C-96/35/90	≥1.0×10 ⁴	1.0×10 ⁶
Volume Resistance 體積電阻	MΩ-cm	2.5.17.1	C-96/35/90	≥1.0×10 ⁶	1.0×10 ⁸
Dielectric Constant 介電常數	—	2.5.5.2	Etched/@1 MHZ	≤5.4	4.6
Loss Tangent 介質損耗	—	2.5.5.2	Etched/@1 MHZ	≤0.035	0.023
Arc Resistance 耐電弧性	Sec	2.5.1	D-48/50+D-0.5/23	≥60	125
Moisture Absorption 吸水率	%	2.6.2.1	D-24/23	≤0.5	0.25
Comparative Tracking Index 相比漏電起痕指數	V	IEC 112	Etched/0.1% NH ₄ Cl	AABUS	175/300/600

Remarks: Specimen Thickness:1.6mm ，樣品厚度：1.6mm

A=Maintain original shape,do not make handling 保持原樣,不作處理

C= Temperature and humidity conditioning 在恒溫恒濕的空氣中處理

E=Temperature conditioning 在恒溫的空氣中處理

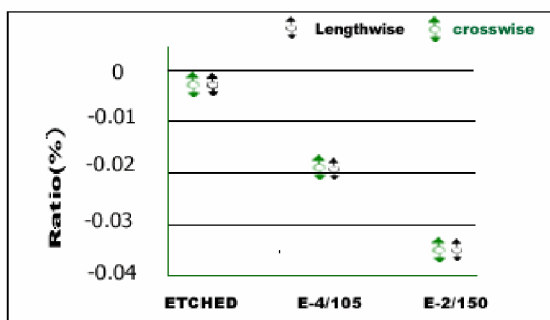
D= Temperature conditioning immersion in distilled water. 浸在恒溫的水中處理

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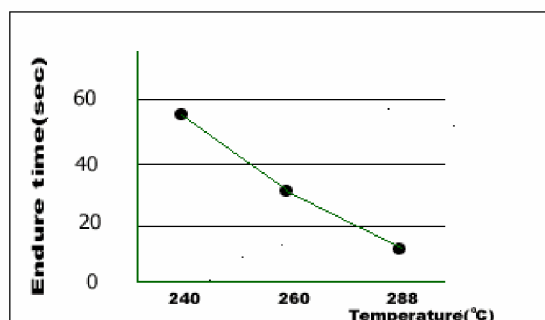
覆銅箔改性環氧紙芯玻璃布複合基層壓板

Speciality Chart 板材特性圖

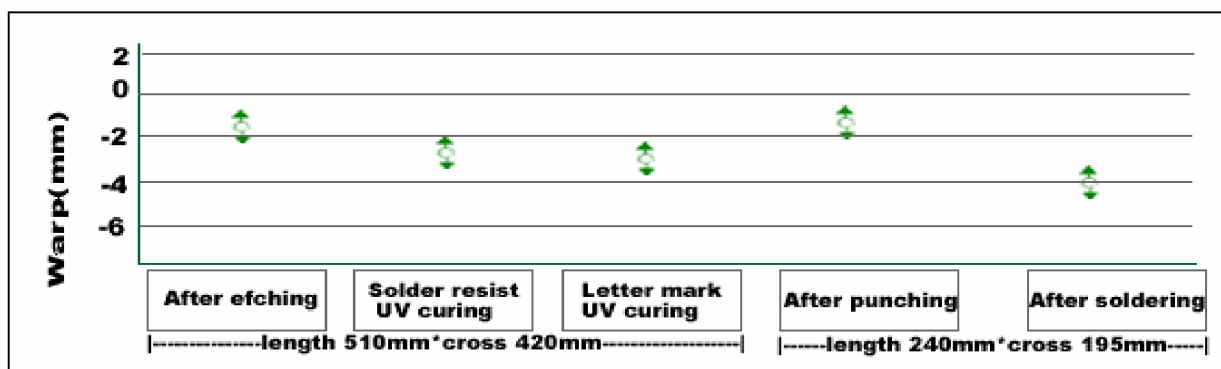
Dimensional stability 尺寸穩定性



Thermal stress 耐熱衝擊性



Warpage through PCB process (thickness 1.6mm single side)



應用領域

- 顯示器、錄影機、電源基板、工業儀錶、數碼刻錄機等

Applications

- Display, VCR, Power supply, Industrial Instrument, Digital sound recorder, etc.

Purchasing Information / 採購資訊

KB-5150 Type 類型	Thickness 厚度	Copper Cladding 銅箔厚度	Regular Size (mm) 常規尺寸	CTI Value CTI 值
CEM-1W (基材呈白色)	0.8mm ~	18μm	1020*1220mm (40"*48")	175V
CEM-1F (基材呈黃色)	1.6mm	35μm	1067*1220mm (42"*48")	300V
		70μm.	915*1220mm (36"*48")	600V

Note: Other sheet size and thickness could be available upon request.

可根據客戶要求提供其他尺寸和厚度。